STEREO IMPACT

PROBLEM REPORT PR-1017 SEP LVPS FM2 Aug 5,2004

PR Numbers: 1x 6xxx=CESR, 7xx	xx=UCB, 2xxx=Caltech/JPL, 3xxx= x=Keil, 8xxx=ESTEC, 9xxx=MPAe	-UMd, 4xxx=GSFC/SEP, 5xxx	x=GSFC/Mag,
Assembly : STEREO SEP LVPS FM2		SubAssembly : SEP Middle	
Component/Part Number: SEP Middle		Serial Number: FM2	
Originator: Selda Heavner		Organization: UC Berkeley	
Phone : 510 643-8640		Email : selda@ssl.berkeley.edu	
Failure Occurred $$ Functional test	During (Check one √) Qualification test	S/C Integration	Launch operations
Environment whe	n failure occurred:		
Ambient	Vibration	Shock	Acoustic
$\sqrt{\text{Thermal}}$	Vacuum	Thermal-Vacuum	EMI/EMC

Problem Description

SEP LVPS FM2 was placed in the temp chamber. The thermal test started with -40° C with nitrogen flowing into an antistatic bag. When the cold temperature test was successfully completed the UUT was left at 25°C for an hour. The functional test was repeated at 25°C. The UUT passed the test. Then the chamber temperature was increased to +50°C. The unit was left in the chamber for an hour. When the power was turned on SEPT-E 5.3V output was 6.3V with load.

Analyses Performed to Determine Cause

The UUT was left at room temperature for an hour and powered on again after the failure occurred. The problem was repeated. SEP LVPS FM2 was disassembled. The drain waveforms of Q22 and Q15 were not as expected. The jumping wire for U27 (54AC109 flip-flop) per rework dated April 02, 04 was crushed. The resistance from pin 7 to ground was measured as $0.73K\Omega$ where the properly functioning pins measured as $2.6M\Omega$.. Only the U21 and U27 parts were stressed and need to be replaced.



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Corrective Action/ ResolutionRepairUse As IsScrap

1- Removed and replaced U27.

 $\sqrt{\text{Rework}}$

- 2- Removed and replaced U21.
- 3- Removed the damaged wire. Rerouted wires to avoid crushing.
- 4- Staked the wires with Uralane 5753 to avoid any movement.
- 5- Completed board level tests. Repeated box level thermal test.

 Date Action Taken:
 August 12, 2004
 Retest Results: Successfully completed board

 level tests and repeated thermal tests.
 Successfully completed box level tests.

 Corrective Action Required/Performed on other Units
 Serial Number(s):
 n/a_____

Closure Approvals				
Subsystem Lead: IMPACT Project Manager: IMPACT QA: NASA IMPACT Instrument Manager:	Date: Date Date: Date: Date:			